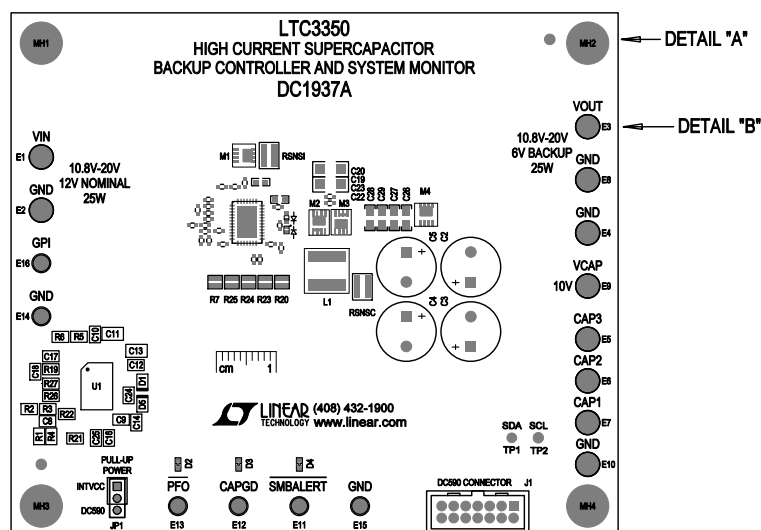
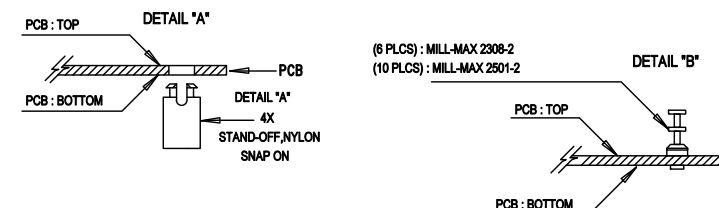


REVISION HISTORY				
ECO	REV	DESCRIPTION	APPR	DATE
-	2	PRODUCTION	MM	5-23-14

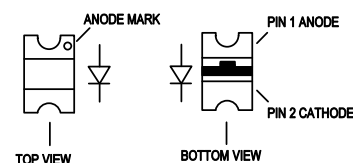


NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY REFLOW PROFILE SHALL BE IN ACCORDANCE WITH J-STD-020 WITH MAXIMUM SOLDER TEMPERATURE OF 250 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS
LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER.
MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. APPLY ASSEMBLY STAMP OR QA STAMP TO BOTTOM OF BOARD (UNSHOWY AREA).
7. INSTALL TURRETS, STAND-OFFS AND BANANA JACKS AS SHOWN BELOW:



8. INSTALL LED'S D2, D3 AND D4 AS SHOWN:



APPROVALS		LINEAR TECHNOLOGY		
PCB DES.	NC	TITLE: TOP ASSEMBLY DRAWING: HIGH CURRENT SUPERCAPACITOR BACKUP CONTROLLER AND SYSTEM MONITOR		
APP ENG.	MM			
		SIZE	IC NO. LTC3350EUHF	REV.
		N/A	DEMO CIRCUIT 1937A	2
SCALE = NONE		FILENAME: DC1937A-2.PCB		SHT 1 of 2